

IN THE CLAIMS

Each claim of the application is set forth below with a parenthetical notation immediately following the claim number indicating the claim status. The Examiner's entry of the claim amendments under Section 1.121 is respectfully requested.

1. (CURRENTLY AMENDED) A process for fabricating an integrated circuit structure comprising:

forming a first contact region selected from the group consisting of a source contact region and a drain contact region of a semiconductor device in a semiconductor substrate;

forming a multilayer stack comprising at least three layers of material over the first contact region, wherein the second layer is interposed between the first and the third layers and wherein the first layer is proximate the first contact region;

forming a window in the at least three layers of material, wherein the window does not extend into the first contact region;

forming a semiconductor material along at least one vertical wall of the window, wherein the semiconductor material comprises vertically-oriented first, second and third doped regions, and wherein the first doped region is adjacent the first layer and further is in electrical contact with the first contact region, and wherein the ~~a~~ second doped region of the semiconductor material is adjacent the second layer, and wherein the third doped region is adjacent the third layer;

forming an insulating material on the inwardly-facing surface of at least the first and the third doped regions in the window;

removing the second layer, thereby exposing at least a portion of the second doped region; and

forming a gate dielectric layer in contact with the second doped region; and

forming a gate in contact with said gate dielectric layer.

2. (ORIGINAL) The process of claim 1 wherein the second layer is removed by etching in an etchant, characterized by a first layer etch rate, a second layer etch rate, and a third layer etch rate, wherein the second layer etch rate is at least ten times faster than one of the first layer etch rate and the third layer etch rate.

3. (ORIGINAL) The process of claim 1 wherein the material of the first layer and the third layer comprises an electrically insulating material.

4. (ORIGINAL) The process of claim 3 wherein the electrically insulating material of at least one of the first and the third layers is doped silicon dioxide for doping, respectively, the first doped region and the third doped region, wherein the process further comprises doping at least one of the first and the third doped regions of the semiconductor material by diffusing dopant from the adjacent first layer or the adjacent third layer.

5. (ORIGINAL) The process of claim 1 wherein the semiconductor material is doped in situ, and wherein the material of at least one of the first layer and the third layer is doped silicon dioxide for doping the first doped region and the third doped region, respectively, and wherein the process further comprises counterdoping at least one of the first and the third doped regions of the semiconductor material by diffusing dopant from the adjacent first layer or the adjacent third layer.

6. (ORIGINAL) The process of claim 1 wherein the semiconductor material comprises crystalline semiconductor material and is selected from the group consisting of silicon, silicon germanium, and silicon-germanium-carbon.

7. (ORIGINAL) The process of claim 1 further comprising forming a second contact region selected from the group consisting of a source contact region and a drain contact region overlying the third doped region, wherein one of the first and second contact regions is a source contact region and the other is a drain contact region.

8. (ORIGINAL) The process of claim 1 wherein the step of forming the semiconductor material further comprises:

forming polycrystalline silicon along at least one vertical wall region of the window;  
and

melting the polycrystalline silicon to form single-crystalline silicon, wherein the material of the first and the third layers is doped insulating material, and wherein during the step of melting the polycrystalline silicon, dopants in the first layer diffuse into the adjacent region of the semiconductor material to form the first doped region, and dopants in the third layer diffuse into the adjacent region of the semiconductor material to form the third doped region.

9. (ORIGINAL) The process of claim 1 further comprising forming an insulating layer over the first layer of material, or over the second layer of material, or over both the first and the second layers of material.

10. (ORIGINAL) The process of claim 9 wherein the insulating layer comprises an etch stop layer.

11. (ORIGINAL) The process of claim 10 wherein a first layer of insulating material is formed over the first layer and a second layer of insulating material is formed over the second layer, and wherein the first and the second layers of insulating material comprise diffusion barriers, and wherein the material of the first layer is doped silicon dioxide that serves as a dopant source for the first doped region and the material of the third layer is doped silicon dioxide that serves as the dopant source for the third doped region, and wherein the process further comprises doping the first doped region of the semiconductor material by diffusing dopant from the first layer and doping the third doped region of the semiconductor material by diffusing dopant from the third layer, and wherein the diffusion barrier presented by the first layer of insulating material effectively prevents the upward diffusion of dopants from the first layer, and wherein the diffusion barrier presented by the second layer of insulating material effectively prevents the upward diffusion of dopants from the third layer.

12. (ORIGINAL) The process of claim 1 wherein the window has a generally circular or ellipsoidal cross section in a plane parallel to the top surface of the semiconductor substrate, and wherein the semiconductor material is formed adjacent the inner wall of the window, and wherein the first, the second and the third doped regions comprise stacked annular rings of the semiconductor material adjacent the inner wall of the window.

13. (ORIGINAL) The process of claim 1 wherein the window has a generally rectangular cross section along a plane parallel to the top surface of the semiconductor substrate, and wherein two insulated regions of semiconductor material are formed adjacent opposing inner wall regions of the window, and wherein the first, the second and the third doped regions are formed in each one of the two regions of semiconductor material, such that two parallel vertical silicon-on-insulator transistors are formed.

14. (ORIGINAL) The process of claim 1 wherein the step of forming insulating material in the window further comprises forming an insulating plug in the open volume of the window.

15. (ORIGINAL) The process of claim 1 further comprising forming insulating material on the inside surface of the first and the third doped regions and forming conductive material on the inside surface of the second doped region.

16. (ORIGINAL) The process of claim 15 wherein the conductive material is connected to ground.

17. (ORIGINAL) The process of claim 15 further comprising:

forming insulating material on the inside surface of the first, second and third doped regions, wherein the insulating material is formed with a greater thickness on the inside surface of the first and the third doped regions due to the dopant concentration in the first and the third doped regions relative to the dopant concentration in the second doped region;

removing the insulating material on the inside surface of the second doped region such that insulating material remains on the inside surface of the first and the second doped regions; and

forming conductive material in electrical contact with the inside surface of the second doped region and electrically separated from the first and the third doped regions by the insulating material.

18. - 22. (CANCEL)

23. - 34. (CANCEL)